

Ersa Dip&Print Station

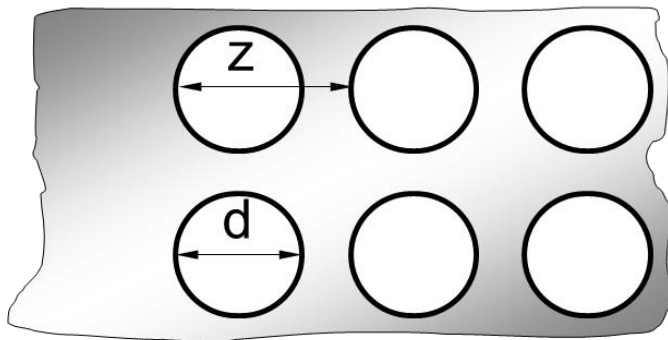
Form dimensional properties for stencil order

Dimensional properties for Print-Stencils for BGA (without pocket):

For correct dimensioning of a solder paste print stencil for BGA with regular ball grid (without component pocket) following points have to be checked:

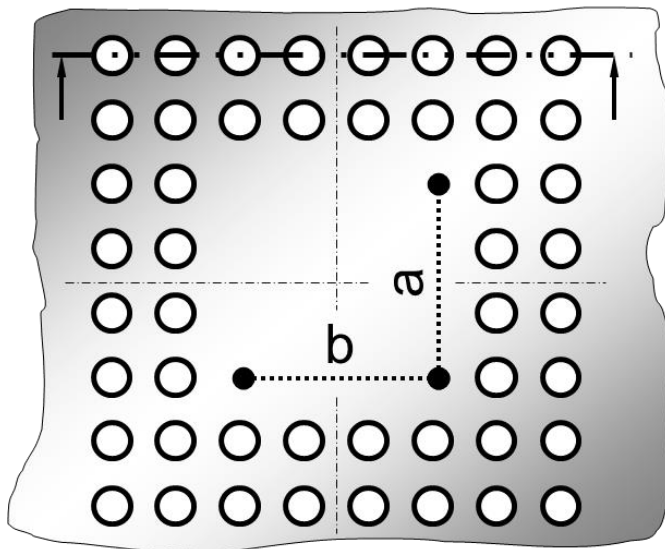
- **How large are the BGA balls?**

The apertures of the stencil have to rest on top of the ball. Enough space has to be left for solder paste application.



d = Aperture diameter

z = Aperture pitch



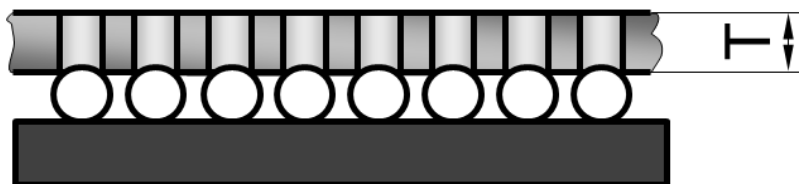
v = Amount of apertures X

w = Amount of apertures Y

a = Amount of free rows

b = Amount of free columns

T = Stencil thickness



- **How high soldering paste has to be printed?**

The height of the soldering paste print defines the deposition quantity largely. Commonly the print height (and the aperture sizes) should be similar to the print stencil used during production. Goal is to achieve the same volume which means the same solder amount.

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Form dimensional properties for stencil order

Please fill the desired measures to the table:

d		mm	Aperture diameter	
z		mm	Aperture pitch	
T		μm	Stencil thickness	If not defined: Standard stencil thickness 120 μm
v		Pieces	Amount of apertures in X	
w		Pieces	Amount of apertures in Y	
a		Pieces	Amount of free rows	
b		mm	Amount of free columns	

Tolerance of all measures, except T: - 0.00 mm + 0.25 mm

Tolerance T: - 10 μm + 10 μm